



**Alfa-MOS
Technology**

**AFP2125S
200V P-Channel
Enhancement Mode MOSFET**

General Description

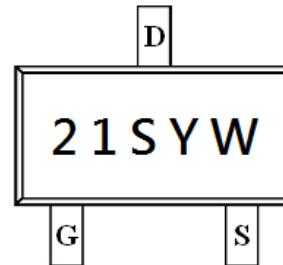
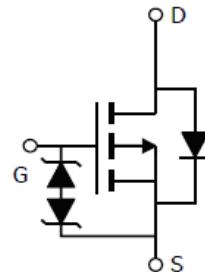
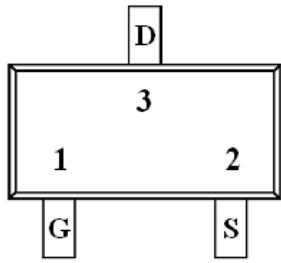
AFP2125S, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

Features

- $I_D = -0.5A, R_{DS(ON)} = 2400 \text{ m}\Omega @ V_{GS} = -10V$
- $I_D = -0.3A, R_{DS(ON)} = 2600 \text{ m}\Omega @ V_{GS} = -4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- ESD Protection (>2KV) Diode design-in
- SOT-23-3L package design

Pin Description (SOT-23-3L)



Application

- Active Clamp Circuits in DC/DC Power Supplies
- Load switch

Pin Define

Pin	Symbol	Description
1	G	Gate
2	S	Source
3	D	Drain

Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFP2125SS23RG	21SYW	SOT-23-3L	Tape & Reel	3000 EA

※ 21S parts code

※ Y year code (0 ~ 9)

※ W week code (A ~ Z = 1 ~ 26 / a ~ z = 27 ~ 52)

※ AFP2125SS23RG : 7" Tape & Reel ; Pb- Free ; Halogen –Free



**Alfa-MOS
Technology**

**AFP2125S
200V P-Channel
Enhancement Mode MOSFET**

Absolute Maximum Ratings

($T_A=25^\circ\text{C}$ Unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-200	V
Gate -Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current($T_J=150^\circ\text{C}$)	I_D	-0.5	A
$T_c=70^\circ\text{C}$		-0.3	
Pulsed Drain Current	I_{DM}	-1.0	A
Continuous Source Current(Diode Conduction)	I_S	-1.0	A
Power Dissipation	P_D	3.2	W
$T_c=70^\circ\text{C}$		2.1	
Operating Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55/150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	120	$^\circ\text{C}/\text{W}$

Electrical Characteristics

($T_A=25^\circ\text{C}$ Unless otherwise noted)

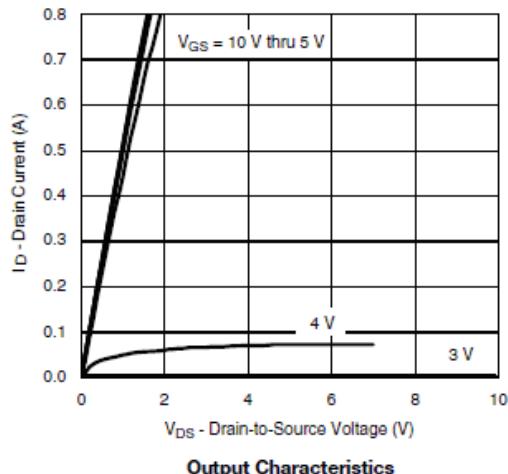
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-200			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.0		-2.5	
Gate Leakage Current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			± 10	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-160\text{V}, V_{GS}=0\text{V}$			-1	μA
$T_J=85^\circ\text{C}$		$V_{DS}=-160\text{V}, V_{GS}=0\text{V}$			-30	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq -10\text{V}, V_{GS}=-10\text{V}$	-0.6			A
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10\text{V}, I_D=-0.5\text{A}$		2000	2400	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-0.3\text{A}$		2100	2600	
Forward Transconductance	g_{FS}	$V_{DS}=-10\text{V}, I_D=-0.5\text{A}$		1.5		S
Diode Forward Voltage	V_{SD}	$I_S=0.3\text{A}, V_{GS}=0\text{V}$		-0.75	-1.2	V
Dynamic						
Total Gate Charge	Q_g	$V_{DS}=-75\text{V}, V_{GS}=-10\text{V}$		10	15	nC
Gate-Source Charge	Q_{gs}			2.5		
Gate-Drain Charge	Q_{gd}			5.0		
Input Capacitance	C_{iss}	$V_{DS}=-75\text{V}, V_{GS}=0\text{V}$ $f=1\text{MHz}$		520	700	pF
Output Capacitance	C_{oss}			30		
Reverse Transfer Capacitance	C_{rss}			20		
Turn-On Time	$t_{d(on)}$	$V_{DD}=-75\text{V}, R_L=75\Omega$ $I_D=-1.0\text{A}, V_{GEN}=-10\text{V}$		10	20	ns
	t_r			12	25	
Turn-Off Time	$t_{d(off)}$			30	60	
	t_f			12	25	



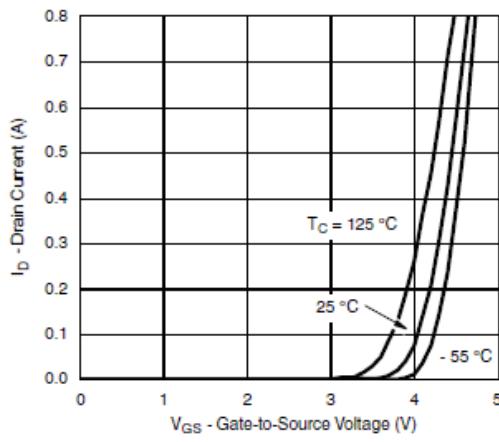
Alfa-MOS Technology

AFP2125S
200V P-Channel
Enhancement Mode MOSFET

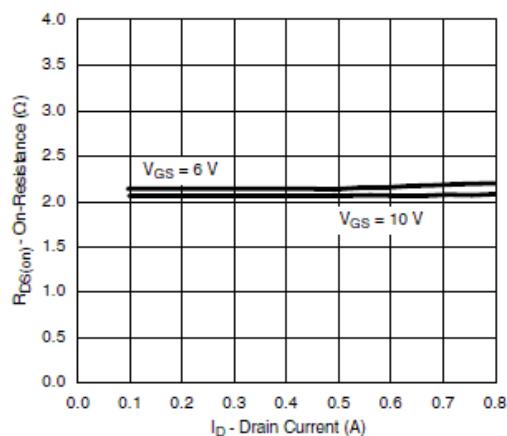
Typical Characteristics



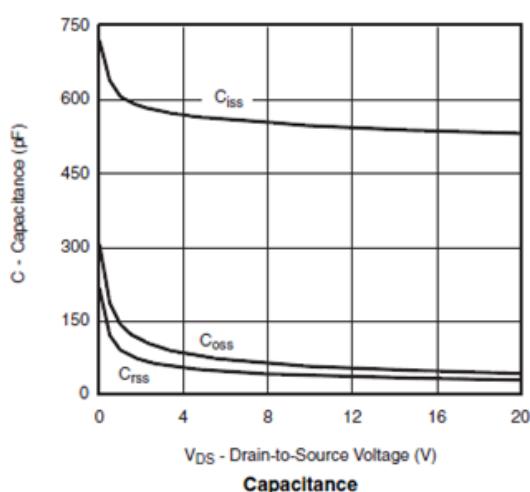
Output Characteristics



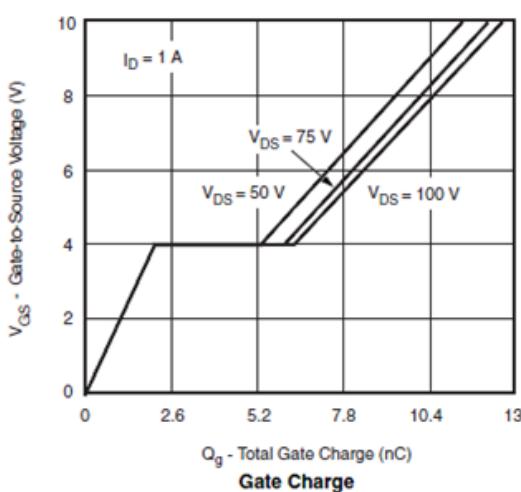
Transfer Characteristics



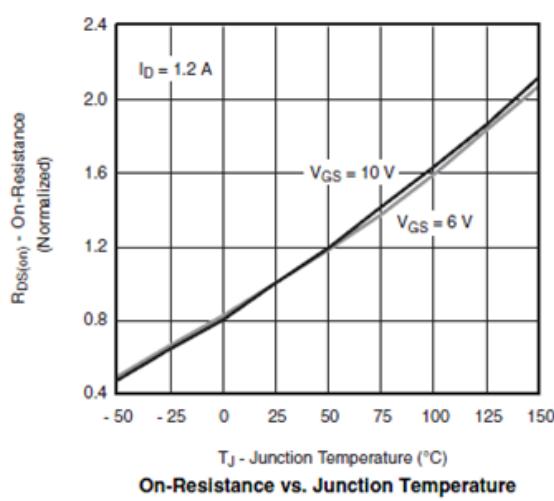
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



Gate Charge



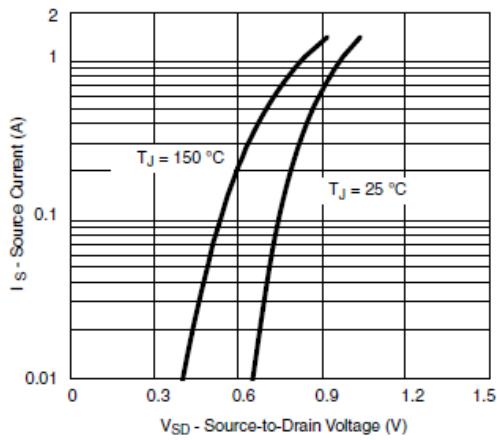
On-Resistance vs. Junction Temperature



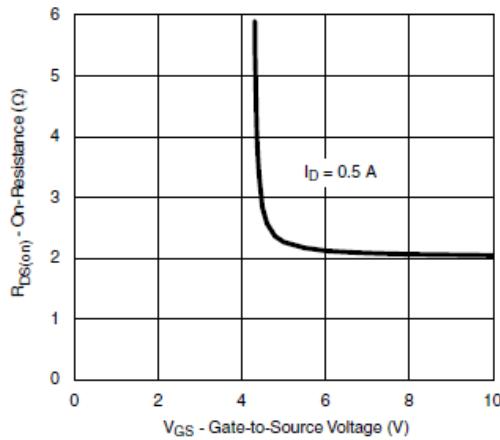
**Alfa-MOS
Technology**

**AFP2125S
200V P-Channel
Enhancement Mode MOSFET**

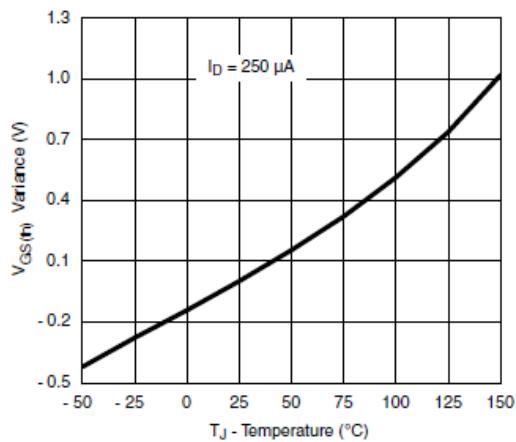
Typical Characteristics



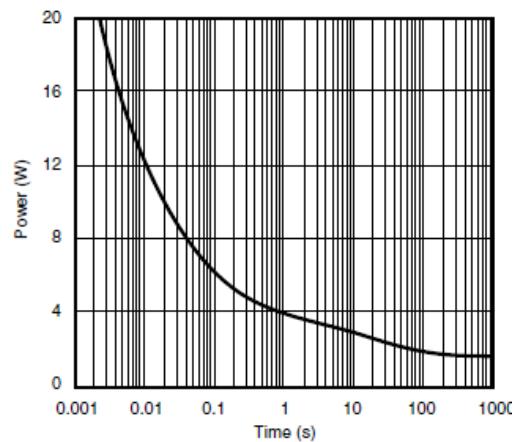
Source-Drain Diode Forward Voltage



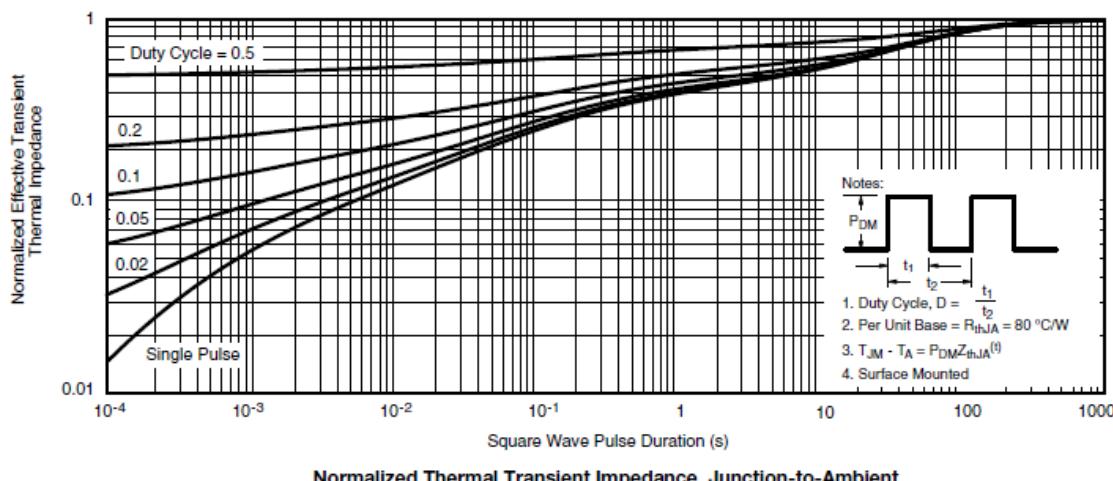
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient

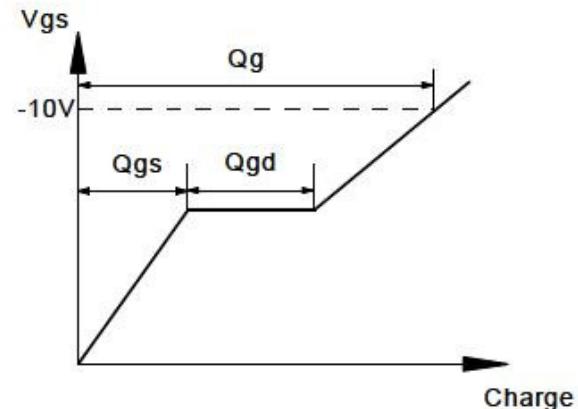
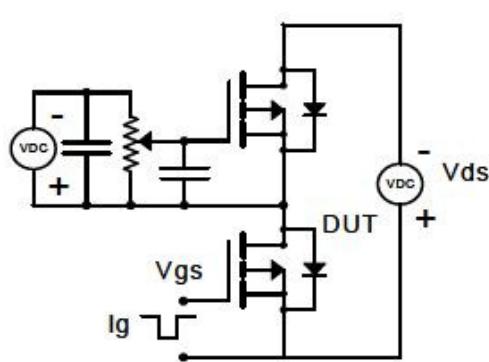


**Alfa-MOS
Technology**

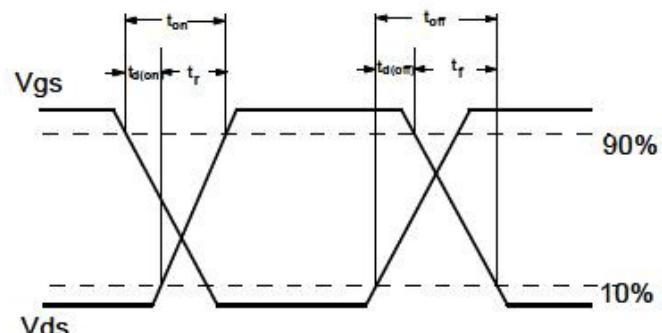
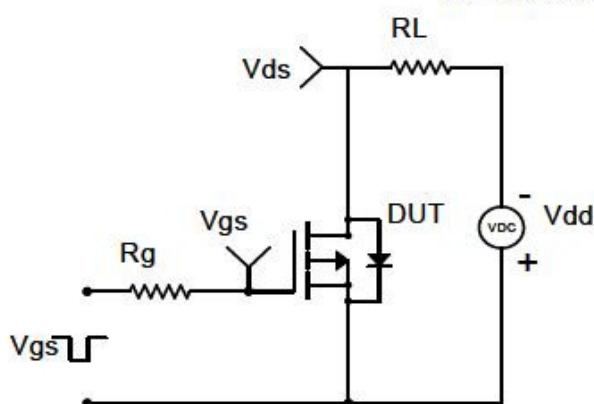
**AFP2125S
200V P-Channel
Enhancement Mode MOSFET**

Typical Characteristics

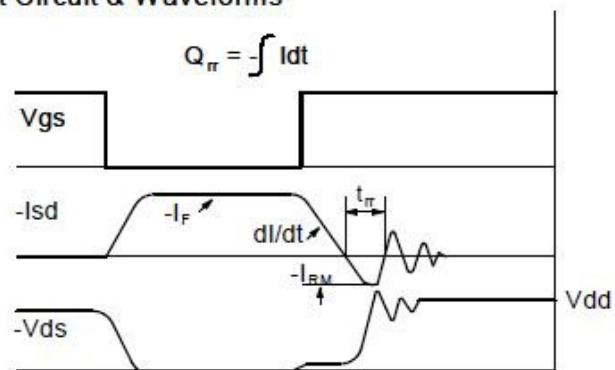
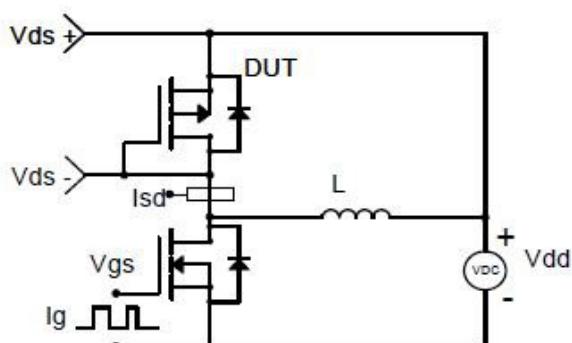
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

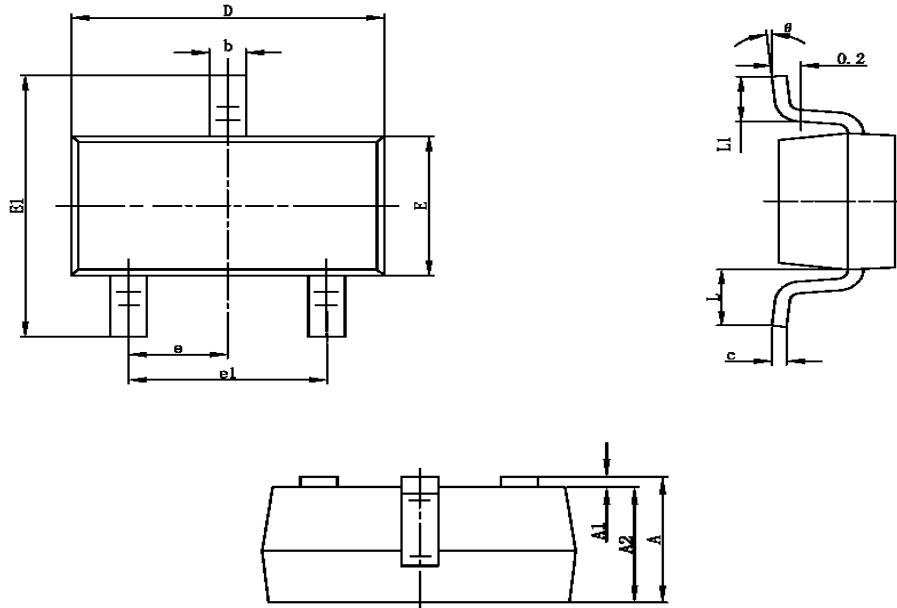




**Alfa-MOS
Technology**

**AFP2125S
200V P-Channel
Enhancement Mode MOSFET**

Package Information (SOT-23-3L)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.400	0.012	0.016
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.700REF		0.028REF	
L1	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

©2010 Alfa-MOS Technology Corp.
2F, No.80, Sec.1, Cheng Kung Rd., Nan Kang Dist., Taipei City 115, Taiwan (R.O.C.)
Tel : 886 2) 2651 3928
Fax : 886 2) 2786 8483
©<http://www.alfa-mos.com>